DuPont™ PlasmaSolv® EKC245™
Post-Etch Residue Remover

DuPont™ PlasmaSolv® EKC245™ post-etch residue remover is made with DuPont™ HDA® hydroxylamine technology for enhanced performance.

Features
- High purity specifications for advanced wafer cleaning
- Removes residues from vias
- Cleans HBr etched polysilicon
- Removes residues after metal etch
- Operates below flashpoint
- Low evaporation rate at operating temperatures
- Does not require ultrasonics
- Rinses in water
- Compatible with automatic equipment
- Great device reliability and product yields
- Lowers via contact resistance
- Maintains gate oxide integrity
- Improves contact between metal layers
- Combines wet chemical processes
- Provides a safe chemical process
- Extends bath life, reduces air emissions, lowers factory operating cost
- Reduces equipment requirements
- Reduces cost of ownership by simplifying process
- Offers flexibility in process